

L Number	Hits	Search Text	DB	Time stamp
-	2	("5489966").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:09
-	56197	semiconductor.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:10
-	73	semiconductor-leading-edge-technologies.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:17
-	2	jp-2001006107-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:23
-	0	jp-20013075598-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:19
-	0	jp-13006107-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:21
-	0	jp-133075598-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:21
-	4	kim-jeong-yeal.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:24
-	409	(250/201.2).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/22 12:50
-	677	(250/204).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:29
-	934	(250/548).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:30
-	562	(250/559.45).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:30

-	1981	(355/53).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/22 12:50
-	1204	(355/55).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:53
-	959	(355/68).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:53
-	578	wafer and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:02
-	13	wafer and 250/204.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:55
-	481	wafer and 250/548.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:55
-	56	wafer and 250/559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:55
-	37	wafer and 250/201.2.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:55
-	111	wafer with edge and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:14
-	165	wafer with edge and 355/53,55,68.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:12
-	17	wafer with edge with exposure and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 14:36
-	64	wafer with edge with exposure and 355/53,55,68.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:21

-	6	wafer with edge with exposure with light and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:21
-	37	wafer with edge with exposure with light and 355/53,55,68.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:32
-	2	jp-09260263-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/22 11:23
-	295	yamada-kohei.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/22 11:09
-	2	jp-61128522-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/22 11:27
-	2591	(250/201.2,204,548,559.45).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 10:30
-	4031	(355/53,55,68).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 10:31
-	3165	(355/53,55).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 10:32
-	2226	(355/53).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 10:32
-	119	wafer with height and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 14:37
-	3	wafer with edge with height and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 14:38
-	203	height and wafer and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 14:38

-	33	(height adj wafer) and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:08
-	10	4870288.URPN.	USPAT	2004/03/10 14:53
-	33	(height adj wafer) and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:09
-	23	optical and sensor and focus and light and ((height adj wafer) and 250/201.2,204,548,559.45.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:29
-	23	height and (optical and sensor and focus and light and ((height adj wafer) and 250/201.2,204,548,559.45.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:29
-	8	height and edge and (optical and sensor and focus and light and ((height adj wafer) and 250/201.2,204,548,559.45.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:29
-	823	(250/559.22,559.27,201.4).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 07:37
-	13216	wafer and (thickness or profile or depth) and focus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 07:38
-	70	wafer and (thickness or profile or depth) and focus and ((250/559.22,559.27,201.4).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 07:54
-	70	wafer and (thickness or profile or depth) and focus and ((250/559.22,559.27,201.4).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 08:03
-	34	wafer and edge and (thickness or profile or depth) and focus and ((250/559.22,559.27,201.4).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 08:03
-	4275	(355/53,55,68).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 10:31
-	2657	(250/201.2,204,548,559.45).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 10:34

-	2451	(355/53).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 10:39
-	1313	(355/55).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 10:45
-	981	(355/68).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/22 10:46